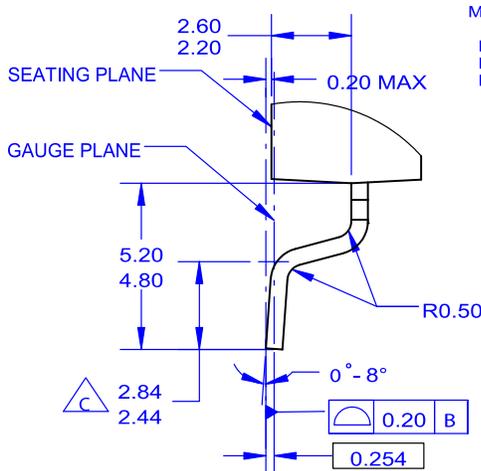
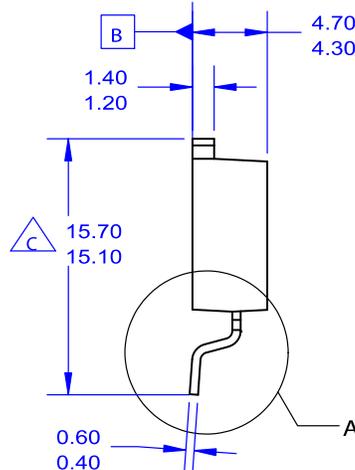
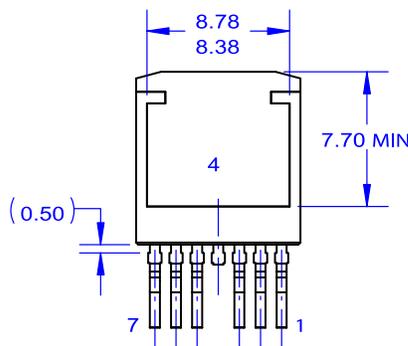
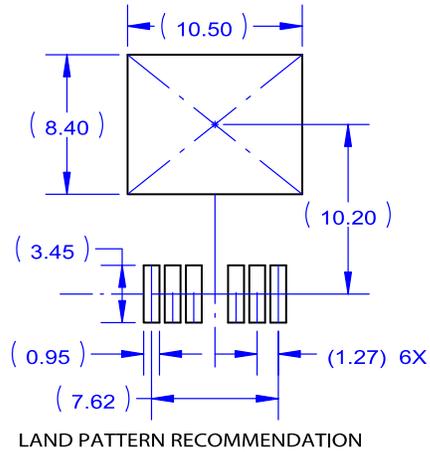
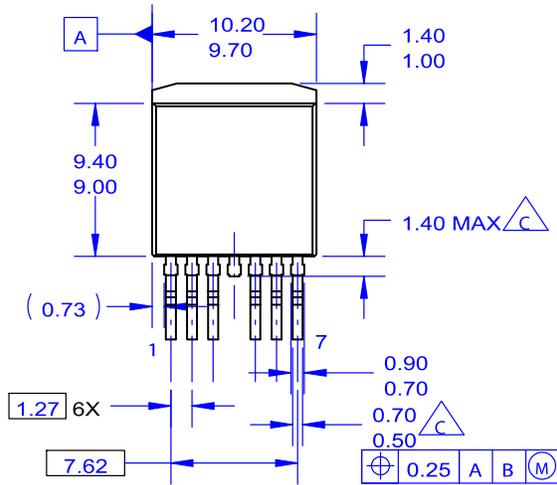




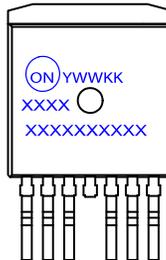
D2PAK7 (TO-263 7 LD)
CASE 418AY
ISSUE A

DATE 11 APR 2018



MARKING:

LINE 1 - LOGO & DATE CODE
 LINE 2 - DEVICE MARKING
 LINE 3 - DEVICE MARKING



PIN1 - GATE
 PIN2 - SOURCE
 PIN3 - SOURCE
 PIN4 - DRAIN
 PIN5 - SOURCE
 PIN6 - SOURCE
 PIN7 - SOURCE

NOTES:

- A. PACKAGE CONFORMS TO JEDEC TO-263 VARIATION CB EXCEPT WHERE NOTED.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. OUT OF JEDEC STANDARD VALUE.
- D. DIMENSION AND TOLERANCE AS PER ASME Y14.5-2009.
- E. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
- F. LAND PATTERN RECOMMENDATION PER IPC, TO127P1524X465-8N.

DETAIL A
SCALE 2:1

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DESCRIPTION:	D2PAK7 (TO-263 7 LD)	PAGE 1 OF 1

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